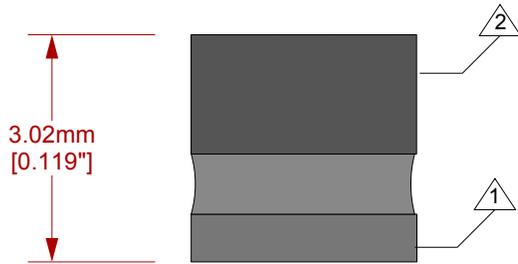


Top View

Side View

Bottom View



Front View

RoHS COMPLIANT

△1 Substrate: 0.635mm ±0.18mm [0.025" ±0.007"] per IPC 4101/21, Gold surface finish.

△2 Substrate: 1.59mm ±0.18mm [0.062" ±0.007"] FR4/G10 or equivalent high temp material. Non-clad.

△3 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.). Contact material- BeCu; finish 0.25µm [10µ"] Au over 2.54µm [100µ"] Ni (min.).

Description: 8 position MLF surface mount foot
8 position (+1 Gnd index pin). 1.0mm pitch UGA female receptacles (top) to 8 position, 0.8mm MLF pattern

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-QFN8C-L-02 Drawing	Status: Released	Scale: 10:1	Rev: A
 <p>© 2005 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: H. Hansen		Date: 12/8/05
	File: SF-QFN8C-L-02 Dwg		Modified: